

Peak Emission Wavelength: 1200nm



Description

- Size 1206: 3.2 (L) x 1.6 (W) x 1.2 (H) mm
- Circuit substrate: glass laminated epoxy
- Devices are RoHS conform
- Lead free solderable, soldering pads: gold plated
- Taped in 8 mm blister tape, cathode to transporting perforation
- Marking at Anode
- High radiation intensity types
- Taping: face-up (TU) or face-down (TD) possible

Absolute Maximum Ratings (Ta=25°C)



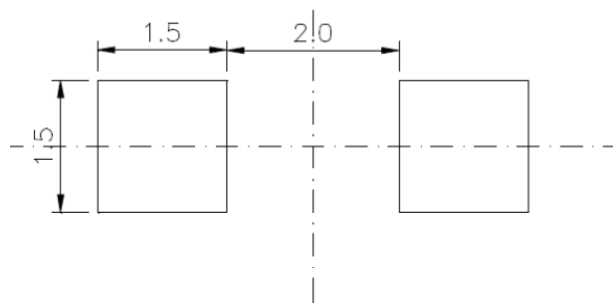
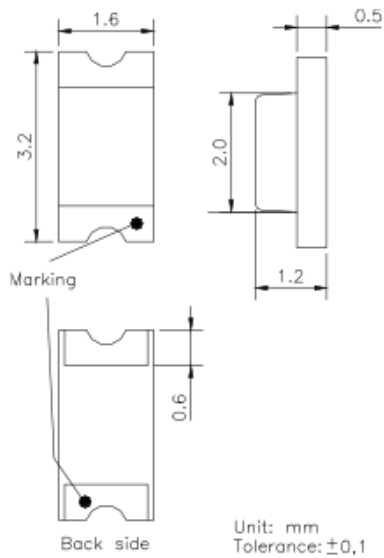
ITEMS	SYMBOL	RATINGS	UNIT
Forward DC Current	If	50	mA
Peak Forward Current *	Ifp	100	mA
Reverse Voltage	Vr	5	V
Reverse Current	Ir	100	uA
Operating Temperature	Top	-40 to +85	°C
Storage Temperature	Tst	-55 to +85	°C
Thermal Resistance	RthJA	450	K/W

* tp ≤ 100 us, T=1ms

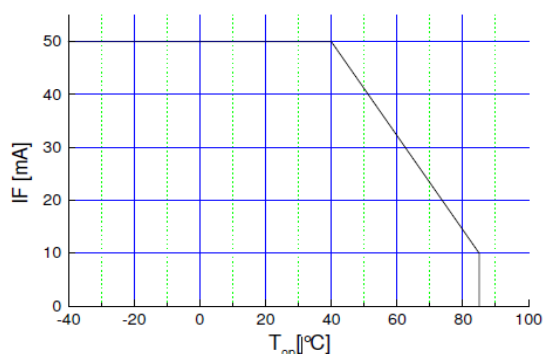
Electrical & Optical Characteristics (Ta = 25°C)

ITEMS	SYMBOL	CONDITION	MIN	TYP	MAX	UNIT
Forward Voltage	Vf	If=50mA	--	1.1	1.5	V
Peak Wavelength	λp	If=50mA	1150	1200	1250	nm
Radiant Power	Φe	If=50mA	--	11	--	mW
Radiant Intensity	Ie	If=50mA	--	2.1	--	mW/sr
Spectral Bandwidth	Δλ0.5	If=50mA	--	73	--	nm
Viewing Angle	φ	If=50mA	--	120	--	deg

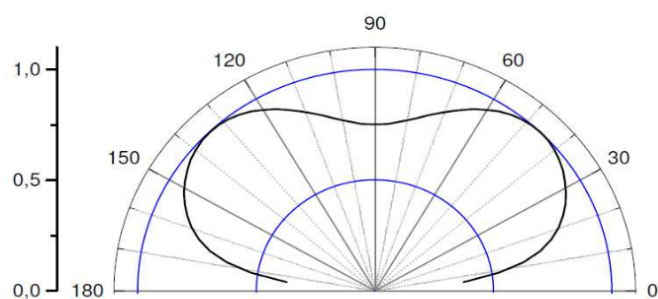
Package Dimensions



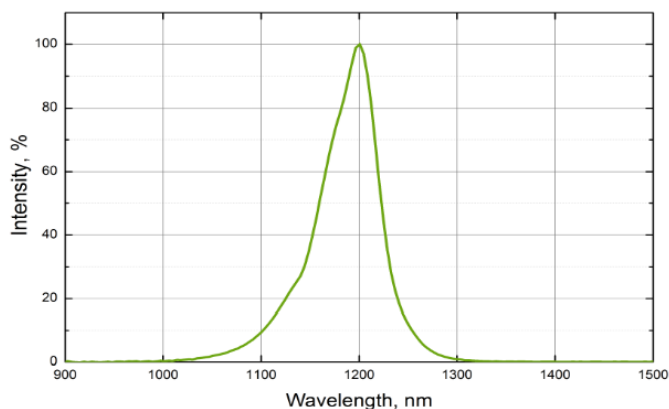
Recommended Soldering Pattern



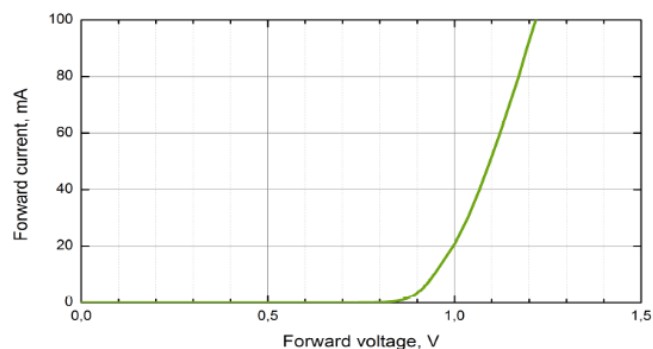
**Maximal
forward
current (DC)
characteristic**



View angle



Typical spectrum at 50 mA



Forward current vs. forward voltage

